

PEEK-SGC301F20

Polyetheretherketone (PEEK)

TECHNICAL DATA SHEET

Description

Sciengy® PEEK-SGC301F20 is a 30% carbon fiber reinforced PEEK compound, standard flow, developed to provide higher strength, wear resistance, low coefficient of friction and chemical resistant.

CF30%, Standard

| | |
|------------------------|-------------------------|
| Series | Carbon fiber reinforced |
| ISO Designation | >PEEK-CF30< |
| Process Method | Injection molding |

Properties

| Physical | Value | Units | Test Standard |
|---|--------------|-------------------|----------------------|
| Density | 1.40 | g/cm ³ | ISO 1183 |
| Mold Shrinkage (Machine Direction) | 0.10 | % | GB/T 15585 |
| Mold Shrinkage (Transverse Direction) | 0.50 | % | GB/T 15585 |
| Water Absorption (23°C-sat) | 0.30 | % | ISO 62 |
| Flammability(1.6 mm) | V-0 | | IEC60695 |
| Mechanical | Value | Units | Test Standard |
| Tensile Stress at Break (5 mm/min) | 255 | MPa | ISO 527 |
| Elongation at Break (23°C) | 1.7 | % | ISO 527 |
| Flexural Modulus at Break (23°C) | 25.0 | GPa | ISO 178 |
| Flexural Strength at Break | 370 | MPa | ISO178 |
| Charpy Impact Strength @23°C (V-notched) | 9.0 | kJ/m ² | ISO 179 |
| Thermal | Value | Units | Test Standard |
| Melting Temperature (10°C/min) | 343 | °C | ISO 11357 |
| Heat Deflection Temp. High Load (1.8 MPa) | 330 | °C | ISO 75 |
| Glass Transition (T _g) | 150 | °C | ISO 11357 |
| Thermal expansion coefficient (T < T _g) along flow | 5.0 | ppm/°C | ISO 11359 |
| Thermal expansion coefficient (T > T _g) along flow | 40 | ppm/°C | ISO 11359 |
| Thermal expansion coefficient (T < T _g) across flow | 6.0 | ppm/°C | ISO 11359 |

PEEK-SGC301F20

Polyetheretherketone (PEEK)

TECHNICAL DATA SHEET

| Thermal expansion coefficient (T>Tg across flow) | 100 | ppm/°C | ISO 11359 |
|--|--|--------|---------------|
| Thermal conductivity (23°C) | 2.0 | W/mk | ISO 22007-4 |
| Electrical Properties | Value | Units | Test Standard |
| Typical Processing Conditions | Value | Units | Test Standard |
| Drying Temp. / Time | 150°C&3h or 120°C&5h(residual moisture<0.02%) | | |
| Injection Molding Melt Temp. | 180°C~210°C | °C | |
| Temperature Settings | 375/385/390/395/395°C(Nozzle) | | |
| Hopper Temperature | Not greater than 100°C | °C | |
| Gate | >2mm or 0.5*part thickness | | |